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An Analysis of Lead-free Final Finishes:
The First Step in Producing a Lead-free Printed Wiring Board

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The electronic industry will be moving to a lead-free package. The first goal will be finding an alternative lead-free solderable surface that can withstand the temperature and assembly requirements for the new lead-free solder alloys. Several solderable lead-free finishes were investigated (thick OSP, silver, tin, electroless nickel and gold). Testing was performed on virgin surface finishes as well as artificial stressed finishes to simulate accelerated aging. The physical, solderable and wetting properties of these finishes were tested using lead containing solder alloys and lead-free alloys.

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